

SID

Factory: Rot am See

Article:

ML6

Provided:

Customer:

Date:

03.04.2026

**WÜRTH
ELEKTRONIK**
MORE THAN
YOU EXPECT

Processtechnology: B: undefined

Material Text	Mat. Nr.	µm	Stackup	Process overview
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A-RS Kupferfolie-018my 330x490mm	50200238	18	VS	1	B00
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	348		2	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		3	
		105	L2		
C-RS-FR4-ML-0.203mm-105+105-TG150-HF-...	50203085	203		4	
		105	L3		
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	304		5	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		6	
C-RAS-FR4-PP-1080-H63-TG150-HF-EM-37B...	50203000	0		7	
		105	L4		
C-RS-FR4-ML-0.203mm-105+105-TG150-HF-...	50203085	203		8	
		105	L5		
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	348		9	
A-RAS-FR4-PP-7628-H45-TG150-HF-EM-37B...	50203002	0		10	
A-RS Kupferfolie-018my 330x490mm	50200238	18	RS	11	

Thickness after Pressing

B00:

1890 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2090 µm

Dmin:

1690 µm

Thickness over all

0 µm

Tol+:

0 µm

Tol-:

0 µm

Dmax:

0 µm

Dmin:

0 µm

Demand for customer

Thickness (D):

2000 µm

Tol+:

200 µm

Tol-:

200 µm

Dmax:

2200 µm

Dmin:

1800 µm

Measuring point: (05) over SM and galv. Cu; both sides

nominal:

1862 µm

Version 1.2.20.35

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